

pSEMI MATERIAL DECLARATION FORM

Product:	PE42522
Ordering Codes:	PE42522B-X
Description:	UltraCMOS® SPDT RF Switch9 kHz – 26.5 GHz
Package:	29L 4x4 LGA
Environmental Compliance	EU RoHS Directive 2011/65/EC, REACH - EU ECHA SVHC, Arsenic Free, JIG 101 - EIA/EICTA/JEITA, Halogen Free - IEC61249-2-21, PFOS Free - 2006/122/EC, Antimony Trioxide Free
Lead Finish	NiPdAu
Availability	Now

Component	Material	CAS Number	Weight (mg)	%	PPM
Die	Aluminum oxide	1344-28-1	1.005204	3.20014%	32,001.38
Die	Aluminum	7429-90-5	0.003058	0.00973%	97.34
Die	Silicon	7440-21-3	0.000204	0.00065%	6.49
Die	Arsenic	7440-38-2	0.000001	0.00000%	0.03
Die	Boron	7440-42-8	0.000001	0.00000%	0.03
Die	Phosphorus	7723-14-0	0.000004	0.00001%	0.13
Die	Titanium	7440-32-6	0.000510	0.00162%	16.22
Die	Tungsten	7440-33-7	0.010192	0.03245%	324.47
Die	Cobalt	7440-48-4	0.000020	0.00006%	0.65
Die	Copper	7440-50-8	0.000008	0.00003%	0.26
Solder Bump	Tin	7440-31-5	0.044749	0.14246%	1,424.61
Solder Bump	Silver	7440-22-4	0.001640	0.00522%	52.21
Solder Bump	Copper	7440-50-8	0.000469	0.00149%	14.92
Solder Bump	Benzocyclobutene	694-87-1	0.000004	0.00001%	0.14
UBM	Aluminum	7429-90-5	0.000101	0.00032%	3.22
UBM	Nickel	7440-02-0	0.000008	0.00002%	0.25
UBM	Vanadium	7440-62-2	0.000107	0.00034%	3.41
UBM	Copper	7440-50-8	0.000280	0.00089%	8.90
Substrate	Bismaleimide	105391-33-1	0.019700	0.06272%	627.16
Substrate	Triazine resin	25722-66-1	0.019700	0.06272%	627.16
Substrate	Epoxy resin	9003-36-5	0.019700	0.06272%	627.16
Substrate	Inorganic Filler	21645-51-2	0.039300	0.12511%	1,251.14
Substrate	Continuous Filament Fiber Glass	65997-17-3	0.039300	0.12511%	1,251.14
Substrate	Copper	7440-50-8	0.059000	0.18783%	1,878.31
Substrate	Nickel	7440-02-0	0.013600	0.04330%	432.97
Substrate	Palladium	7440-05-3	0.000800	0.00255%	25.47
Substrate	Gold	7440-57-5	0.000800	0.00255%	25.47
Molding Compound	Solid Epoxy Resin	Proprietary	3.013300	9.59306%	95,930.57
Molding Compound	Phenol Resin	Proprietary	2.109300	6.71511%	67,151.08
Molding Compound	Carbon Black	1333-86-4	0.301300	0.95921%	9,592.10
Molding Compound	Metal Hydroxide	Proprietary	0.904000	2.87795%	28,779.49
Molding Compound	Amorphous silica	60676-86-0	22.900900	72.90666%	729,066.61
Molding Compound	Crystalline silica	14808-60-7	0.904000	2.87795%	28,779.49
Total Weight (mg)			31.411259	100.00%	1,000,000